This file has been cleaned of potential threats.

To view the reconstructed contents, please SCROLL DOWN to next page.



प्लाज्मा अनुसंधान संस्थान INSTITUTE FOR PLASMA RESEARCH परमाणु ऊर्जा विभाग, भारत सरकार का एक सहायता प्राप्त संस्थान



An Aided Institute of Department of Atomic Energy, Government of India

इन्दिरा पुल के पास, भाट, गांधीनगर – 382 428 भारत दूरभाष: (079) 2396 2020/2021/2028 फैक्स: 91-079-23962277 वेब: <u>www.ipr.res.in</u> NEAR INDIRA BRIDGE, BHAT DIST. GANDHINAGAR - 382 428 (INDIA) Phone: (079) 2396 2000/2026/2332 Fax : 91-079-23962277 Web : <u>www.ipr.res.in</u>

ENQUIRY	
ENQUIRY NO Date	: IPR/EQF/19-20/094 : 18-07-2019
Due on	: 29-08-2019 by 1:00 PM IST

Please send your offer in sealed envelope specifying Enquiry No, Date & Due Date, ALONG WITH your credentials for the following items which we are interested to import directly against Foreign Trade Policy 2015-2020.

## **Important Note:**

Please note that e-mail quotations are not acceptable however you may send your queries (if any) to <u>importpurchase@ipr.res.in</u>

## Please ensure your sealed quotation reaches this office not later than above mentioned due date and time.

Kindly go through the following documents properly before quoting which are available on the IPR web portal i.e., <u>http://www.ipr.res.in/documents/tender\_terms.html</u> / attached herewith.

- 1) Instructions to the bidders & Terms and conditions (refer Form No: IPR-FP-01.V3)
- 2) Bidding format

**GST for Goods and Services (IGST/CGST/SGST TAX BENEFITS):** Please refer **clause no:** 14 of Form No: **IPR-FP-01.V3** 

## **QUOTATION SHOULD BE ADDRESSED TO PURCHASE OFFICER ONLY**

Sr No	Description	Quantity
	Multi-channel ADC and DAC module with computer interfacing carrier board as per attached specifications	1.0 Nos.
Note:	<ol> <li>Please quote with complete technical details (Technical compliance sheet and product data sheet).</li> <li>2.TDS as per CGST Act: As per provisions of section No. 51 of the CGST Act 2017, TDS @2% (IGST 2% or CGST 1% and SGST 1%) will be deducted while making payment to the suppliers where total value of orders/contracts/work orders exceeds Rs. 2.5 lakhs, in the event of order in Indian Rupees. Necessary TDS Certificate will be issued to the supplier after TDS deduction.</li> </ol>	
Encl:	As per attached. S	d/-

**Information to Vendors:** We are working towards a single platform for our future requirement. Hence, please refer IPR website i.e, <a href="http://www.ipr.res.in/documents/tenderseng.html">http://www.ipr.res.in/documents/tenderseng.html</a> for our future requirement.

No	IPR specifications	Vendor Response
	Multi-channel ADC and DAC mdule with computer interfacing carrier board	
I	Speicifcations for Analog to digital conversion (ADC) module	
1	Analog input channels: ~ 30 or more	
2	Input type: Single ended (DC)	
3	Sampling frequency: 1 MSps (per channel simultaneous)	
	Bit resolution: ≥ 14-bit	
5	Input voltage range: ± 10 V	
6	Input impedance: ~ 1 MΩ	
7	Analog bandwidth: ≥ 500 KHz	
8	Input connector: BNC type prefered (quote seprately for BNC connector panel)	
	Form factor: FMC type prefered / stand-alone type	
10	Operating temperature: 0° to 40° C	
II	Specifications for Digital to analog conversion (DAC) module	
1	Analog output channels: 4	
2	Sampling rate: ~ 1 MSps	
3	Bit resolution: ≥ 14-bit	
4	Output voltage range: ± 10 V	
5	Output connector: BNC / LIMO (quote seprately for connector panel and cables)	
6	Form factor: FMC type perfered / stand-alone type	
7	Operating temperature: 0° to 40° C	
	Specifications for carrier board / standalone chassis configuration	
1	Carrier type: FMC type carrier prefered or standalone	
2	Input-output connection: clock, trigger, USB / Ethernet	
3	Input power: 230 VAC or ~ 12 V DC	
	Cooling fan: required	
5	LED indication: required	
6	Computer interfacing: Gigbit Ethernet	
	System processor: FPGA / SoC / ARM processor or equivalent	
8	Internal Storage memory: ~ 1 GB	
	Software support	
1	Software: LabVIEW support, Xilinx tool, SDK	
2	Operating system: Windows / Linux	
	* Quote separately for accessories like cables, panels, chassis, power supply, software, etc.	
	Bidder's Official Stamp and Sign:	
	Date:	